

Customer No.: 31561  
Docket No.: 11182-US-PA  
Application No.: 10/710,582

**AMENDMENT**

**In The Claims**

Claim 1. (currently amended) A method of fabricating a flip chip ball grid array (FC-BGA) package, comprising:

providing a substrate having a first circuit surface, a second circuit surface, and a substrate core layer with plurality of openings, wherein the substrate core layer is disposed on the first circuit surface of the substrate;

adhering a plurality of flip chips to the first circuit surface of the substrate through the openings of the substrate core layer;

performing a ball placement step for attaching a plurality of solder balls to the second circuit surface; and

singulating the substrate for separating portions of the substrate having the flip chips adhered thereon, wherein the substrate core layer of the substrate is also removed away due to singulating the substrate.

Claim 2. (previously presented) The method of claim 1, further comprising a glue sealing step for filling a sealing glue material into the openings to cover the flip chips.

**Claims 3-7. (cancelled).**

Claim 8. (previously presented) The method of claim 1, the step of adhering the flip chips to the first circuit surface of the substrate further comprising filling an underfill material between the substrate and the flip chips.